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most industrial and commercial applications will demand high assembly-level reliability from assembled packages. Panasonic has developed a broad range of products for motherboard material and ...

Panasonic develops new semiconductor substrate material Semiconductor package ... requirements of any packaging solution is mechanical integrity and reliability, which has also seen steady improvement through materials and process developments.

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Mechanical Modeling Advances Improve Semiconductor Packaging Experts at the Table: Semiconductor Engineering sat ... black-belt chip design that requires very close interaction with who ' s doing the design, who ' s doing the manufacturing and who ' s doing the ...

CEO Outlook: Chiplets, Longer IC Lifetimes, More End Markets Semiconductor packages used in various vehicle applications require high reliability. As technological innovations ... AEC-Q006 requires specific attention to sensitive packaging areas, including: ...

Qualifying Exposed Pad TQFP For AEC-Q006 Grade 0 The Center for Device Thermography and Reliability (CDTR), led by Professor Martin ... and talks ranging from wide bandgap

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semiconductor materials and devices such as GaN, diamond to two-dimensional ...

Center for Device Thermography and Reliability

Appropriate structures tightly localise incident fields enhancing graphene light-matter interaction ... signal losses in materials used for the antennas, advanced electronics packaging, and ...

45 Million of 5G small cells will be installed by 2031 forecasts

IDTechEx

Presto Engineering, an ASIC design and outsourced operations provider, and Cadence Design Systems, Inc. (Nasdaq: CDNS) today announced a collaboration to broaden semiconductor package design solutions ...

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Presto Engineering and Cadence Collaborate on IC Packaging for Automotive and IoT Markets

That has meant a change in culture around car lots, with in-person interaction between consumers ... for the manufacturing of advanced semiconductor packaging technologies. In addition, President ...

Auto industry, including locals, bearing brunt of worldwide semiconductor shortfall

Companies: 35 - Players covered include AI Technology, Inc.; Alpha Assembly Solutions; BE Semiconductor ... die-attach materials. This process is critical to various kinds of packaging.

Global Die-Attach Materials Market to Reach \$834 Million by 2026

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Radiation shielding and special packaging for ... will be those who can ensure reliability, affordability, quick-turnaround designs, and access to the latest semiconductor technologies.

The evolving world of radiation-hardened electronics for space
Due to mandated restrictions, the majority of customer and employee interactions had ... testing, packaging, inventory and distribution. It further encompasses semiconductor manufacturing equipment, ...

How the Internet of Things Could Help Solve the Chip Shortage
(a) Schematic illustrating thermal management in electronics chip packaging ... of wide bandgap semiconductor devices has led to many advancements of high power and high frequency electronics. However

...

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Cooling high power electronics - boron arsenide spreads heat better than diamond

Ultimately, these companies want suppliers to provide them with LiDAR sensors that are low-cost with a high degree of reliability while meeting ... related to the properties of light and semiconductor ...

Understanding wavelength choice in LiDAR systems

During the last decade, the semiconductor industry has ... because memory bits made from ferromagnetic materials exhibit magnetic field interactions that prevent them from operating reliably ...

A more robust memory device for AI systems

Last month Taiwan Semiconductor Manufacturing Company

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(TSMC) used its 2021 Technology Symposium to unveil a range of new innovations in advanced logic technology, specialty technologies, advanced ...

Master of the Universe

As an alternative to reduce the hardware count, increase reliability ... lasers using this same 'toolbox' of advanced semiconductor and packaging processes may enable higher speeds, longer ...

Optical Advances Help Enable 800 Gigabit Ethernet

Presto is adopting the Cadence ® system design and analysis portfolio for advanced IC packaging ... reliability requirements, tend to require multiple spins in order to optimize the bill of ...

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